

### NCE P-Channel Enhancement Mode Power MOSFET

### **Description**

The NCE20P05J uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages .This device is suitable for use as a load switching application and a wide variety of other applications.

### **General Features**

•  $V_{DS} = -20V, I_{D} = -5A$ 

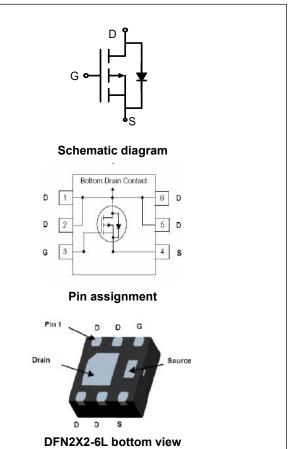
 $R_{DS(ON)} = 65m\Omega @ V_{GS} = -4.5V (Typ)$ 

 $R_{DS(ON)} = 88m\Omega @ V_{GS} = -2.5V (Typ)$ 

- Advanced trench MOSFET process technology
- Ultra low on-resistance with low gate charge

### **Application**

- PWM applications
- Load switch
- Battery charge in cellular handset



### Package marking and ordering information

Device Marking	Device	Device Package	Reel Size	Tape Width	Quantity
NCE20P05J	NCE20P05J	DFN2X2-6L	-	-	-

### Absolute maximum ratings (T<sub>A</sub>=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	VDS	-20	V	
Gate-Source Voltage	Vgs	±12	V	
Drain Current-Continuous	I <sub>D</sub>	-5	А	
Drain Current -Pulsed (Note 1)	I <sub>DM</sub>	-20	Α	
Maximum Power Dissipation	P <sub>D</sub>	2.5	W	
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 150	$^{\circ}$ C	

### **Thermal Characteristic**

Thermal Resistance,Junction-to-Ambient (Note 2)	Reja	50	°C/W
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# Electrical characteristics (T<sub>A</sub>=25 $^{\circ}$ C unless otherwise noted)

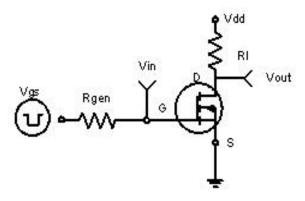
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics				•		
Drain-Source Breakdown Voltage	V <sub>(BR) DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-20	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-20V,V <sub>GS</sub> =0V	-	-	-1	μΑ
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_{D}=-250\mu A$	-0.5	-0.7	-1	V
Donin Course On Otata Danistana		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-5A	-	65	75	mΩ
Drain-Source On-State Resistance			-	88	115	mΩ
Forward Transconductance	<b>g</b> FS	$V_{DS}$ =-5 $V$ , $I_{D}$ =-5 $A$	-	9	-	S
Dynamic Characteristics (Note4)			'			
Input Capacitance	C <sub>lss</sub>	1/ 40)/1/ 0)/	-	496	-	PF
Output Capacitance	Coss	$V_{DS}$ =-10V, $V_{GS}$ =0V, F=1.0MHz	-	140	-	PF
Reverse Transfer Capacitance	Crss	F-1.UIVITIZ	-	86	-	PF
Switching Characteristics (Note 4)				•		
Turn-on Delay Time	t <sub>d(on)</sub>		-	40	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =-10 $V$ , $R_L$ =2 $\Omega$	-	28	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}\text{=-}4.5V, R_{GEN}\text{=}3\Omega$	-	38	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	10	-	nS
Total Gate Charge	Qg	10)// 40	-	7	-	nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> =-10V,I <sub>D</sub> =-1A,	-	1.0	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> =-4.5V	-	1.6	-	nC
Drain-Source Diode Characteristics			,			•
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =-5A	-	-	-1.2	V
Diode Forward Current (Note 2)	Is		-	-	-5	Α

### Notes:

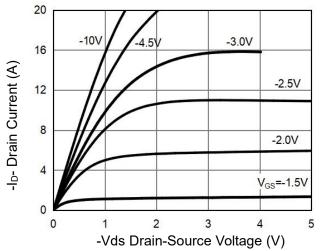
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.
- **3.** Pulse Test: Pulse Width ≤  $300\mu$ s, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production



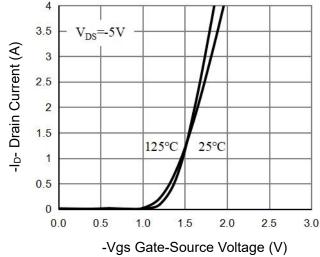
## **Typical Electrical and Thermal Characteristics**



**Figure 1:Switching Test Circuit** 



**Figure 3 Output Characteristics** 



**Figure 5 Transfer Characteristics** 

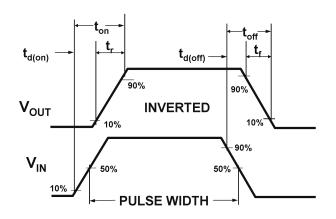


Figure 2:Switching Waveforms

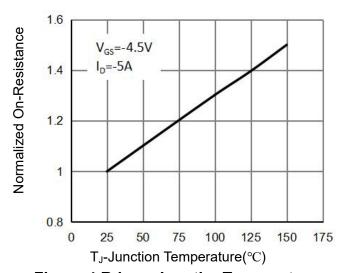


Figure 4 Rdson-JunctionTemperature

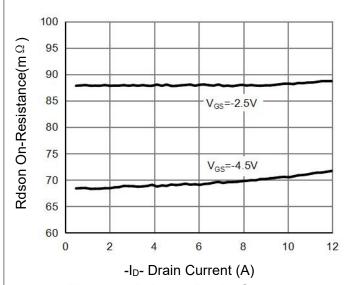


Figure 6 Rdson- Drain Current



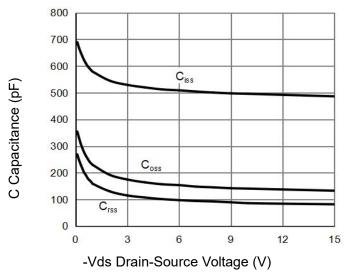


Figure 7 Capacitance vs Vds

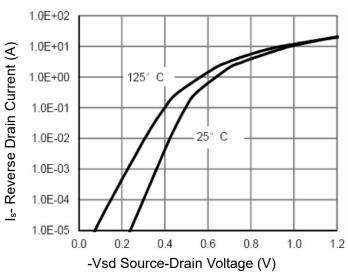
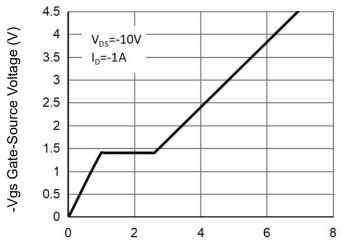


Figure 8 Source- Drain Diode Forward



**Qg Gate Charge (nC) Figure 9 Gate Charge** 

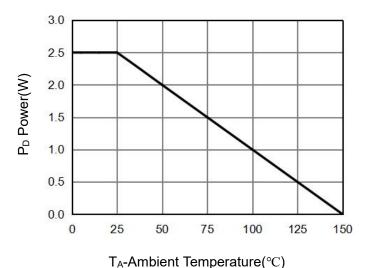
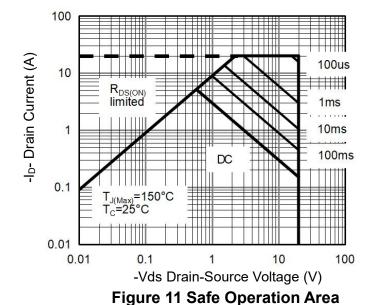
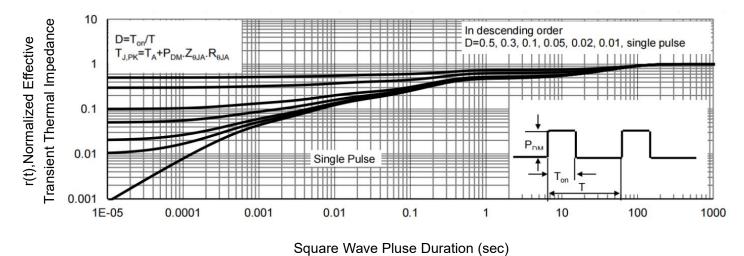


Figure 10 Power Dissipation



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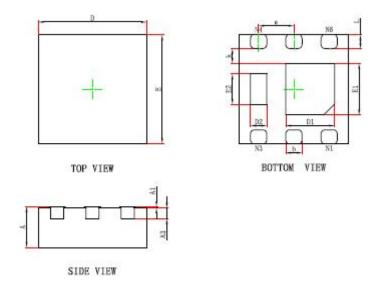




**Figure 12 Normalized Maximum Transient Thermal Impedance** 



### **DFN2X2-6L Package Information**



Symbol	Dimensions In	n Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	0.700	0.800	0.028	0.031	
A1	0.000	0.050	0.000	0.002	
A3	0.2031	0.203REF.		REF.	
D	1.924	2.076	0.076	0.082	
E	1.924	2.076	0.076	0.082	
D1	0.800	1.000	0.031	0.039	
E1	0.850	1.050	0.033	0.041	
D2	0.200	0.400	0.008	0.016	
E2	0.460	0.660	0.018	0.026	
k	0.200MIN.		0.008MIN.		
b	0.250	0.350	0.010	0.014	
е	0.650TYP.		0.026TYP.		
L	0.174	0.326	0.007	0.013	

### **Notes**

- 1. All dimensions are in millimeters.
- 2. Tolerance ±0.10mm (4 mil) unless otherwise specified
- 3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
- 4. Dimension L is measured in gauge plane.
- $5. \ Controlling \ dimension \ is \ millimeter, \ converted \ inch \ dimensions \ are \ not \ necessarily \ exact.$



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